

## ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

**Title of  
Invention**

Surface Mount Package and Method for Forming Multi-chip  
Microsensor Device

Application Number :

Confirmation Number:

First Named Applicant: WOOJIN KIM

Attorney Docket Number: 65271-027

Art Unit:

Examiner:

Search string: ( 4838089 or 5901046 or 5912556 ).pn

### US Patent Documents

**Note: Applicant is not required to submit a paper copy of cited US Patent Documents**

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	4838089	1989-06-13	OKADA ET AL			
	2	5901046	1999-05-04	OHTA ET AL			
	3	5912556	1999-06-15	FRAZEE ET AL			

### Signature

Examiner Name	Date